


**PRODUCT / PROCESS CHANGE NOTIFICATION**

**1. PCN basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCN No.</b>	ANALOG MEMS SENSORS/25/15203	
<b>1.3 Title of PCN</b>	Qualification of Wafer Bumping Transfer to JCET from ASECL & ATT5	
<b>1.4 Product Category</b>	See product list	
<b>1.5 Issue date</b>	2025-02-05	

**2. PCN Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	PIKE EMMA
<b>2.1.2 Phone</b>	+44 1628896111
<b>2.1.3 Email</b>	emma.pike@st.com
<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	Marcello SAN BIAGIO
<b>2.1.2 Marketing Manager</b>	Salvatore DI VINCENZO
<b>2.1.3 Quality Manager</b>	Jean-Marc BUGNARD

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Methods	(Not Defined)	See condition field

**4. Description of change**

	Old	New
<b>4.1 Description</b>	UBA5 Wafer Bumping at ASECL + ASSY/FT at Shenzhen. U1N2, UQ55 & UBBE Wafer Bumping at ATT5 + ASSY/TNF at ATT3.	UBA5 Wafer Bumping at JCET + ASSY/FT at Shenzhen. U1N2, UQ55 & UBBE Wafer Bumping at JCET + ASSY/TNF at ATT3.
<b>4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?</b>	No impact	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	Bumping process used in ASE and Amkor under termination. Qualification of JCET in order to ensure service continuity
<b>5.2 Customer Benefit</b>	SERVICE CONTINUITY

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	New genealogy
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**7. Timing / schedule**

<b>7.1 Date of qualification results</b>	2025-02-03
<b>7.2 Intended start of delivery</b>	2025-05-10
<b>7.3 Qualification sample available?</b>	Upon Request

**8. Qualification / Validation**

<b>8.1 Description</b>	15203 PCN report_bumping-2025.pdf		
<b>8.2 Qualification report and qualification results</b>	Available (see attachment)	<b>Issue Date</b>	2025-02-05

**9. Attachments (additional documentations)**

15203 Public product.pdf  
15203 PCN report\_bumping-2025.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	ST1PS01AJR	
	ST1PS01BJR	
	ST1PS01DJR	
	ST1PS01EJR	
	STBC02AJR	
	STBC02JR	
	STLQ020J33R	

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